2SA673(A)

Rev.E Mar.-2016

DATA SHEET

/ Descriptions

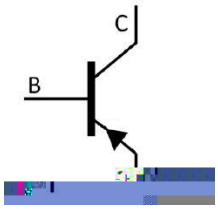
WR0<5 ṂṂÞ SQS ÆḾч s Ⅱㄱ Silicon PNP transistor in a TO-92 Plastic Package.

лъ 5VF4546+D,Ӣ´

Complementary pair with 2SC1213(A).

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Low frequency power amplifier.





PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

/ hFE Classifications & Marking

/ Absolute Maximum Ratings(Ta=25)

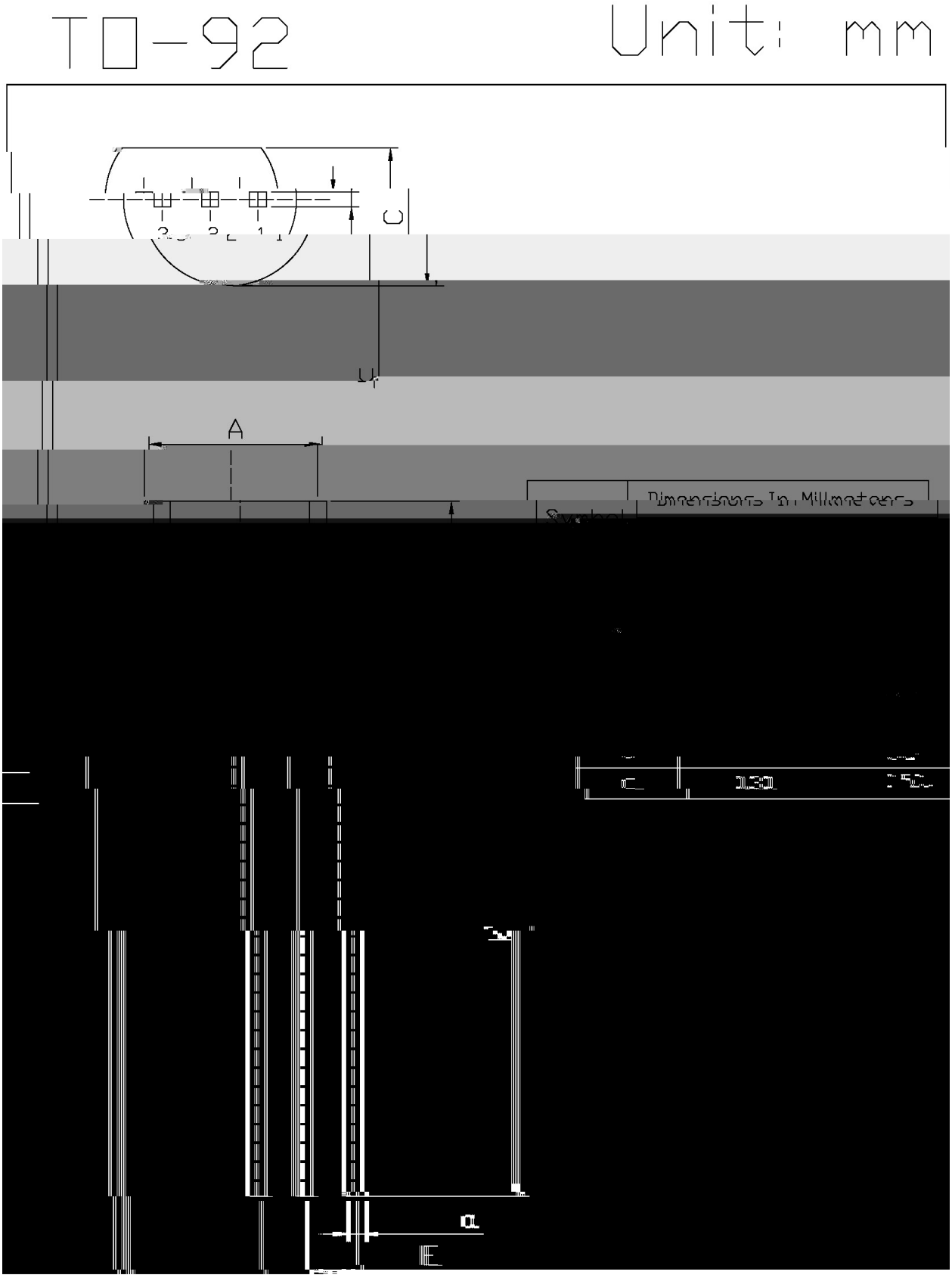
v ̈Ω Parameter	ϒ N Symbol		̈Ω Ö Rating	D Ɥ Unit
Collector to Base Voltage	V_{CBO}	2SA673	-35	V
		2SA673A	-50	
Collector to Emitter Voltage	V_{CEO}	2SA673	-35	V
		2SA673A	-50	
Emitter to Base Voltage	V_{EBO}		-4.0	V
Collector Current - Continuous	I_C		-500	mA
Collector Power Dissipation	P_C		400	mW
Junction Temperature	T_j		150	
Storage Temperature Range	T_{stg}		-55 150	

/ Electrical Characteristics(Ta=25)

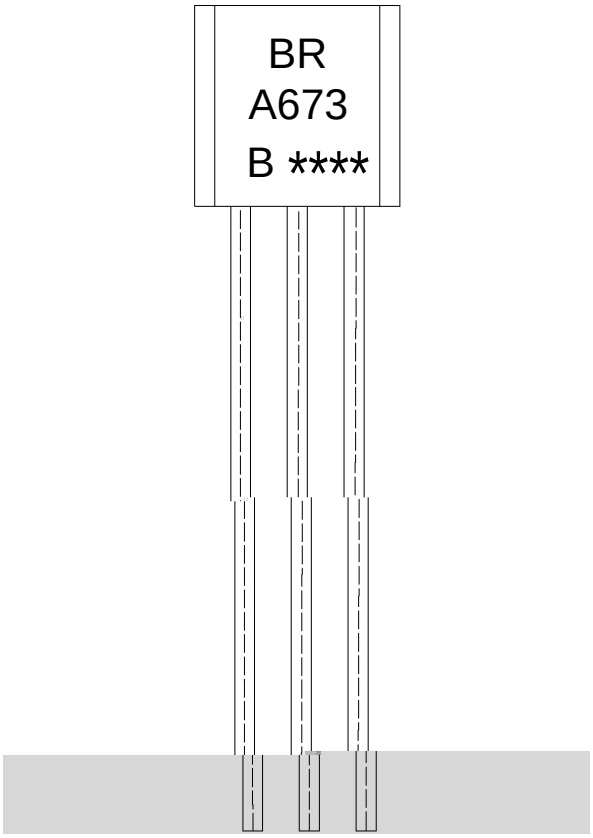
v ̈Ω Parameter	ϒ N Symbol		╨ :ϯ ϯ Test Conditions	ω ŋ Ö Min	Ɛ ʒ Ö Typ	ω ᶻ Ö Max	D Ɥ Unit
Collector to Base Breakdown Voltage	V_{CBO}	2SA673	I_C=-10 A I_E=0	-35			V
		2SA673A		-50			
Collector to Emitter Breakdown Voltage	V_{CEO}	2SA673	I_C=-1.0mA I_B=0	-35			V
		2SA673A		-50			
Emitter to Base Breakdown Voltage	V_{EBO}		I_E=-10 A I_C=0	-4.0			V
Collector Cut-Off Current	I_{CBO}		V_{CB}=-20V I_E=0			-0.5	A
DC Current Gain	$h_{FE(1)}$		V_{CE}=-3.0V I_C=-10mA	60		320	
	$h_{FE(2)}$		V_{CE}=-3.0V I_C=-500mA	10			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$		I_C=-150mA I_B=-15mA		-0.2	-0.6	V
Base to Emitter Voltage	V_{BE}		V_{CE}=-3.0V I_C=-10mA		-0.64		V



/ Package Dimensions



/ Marking Instructions



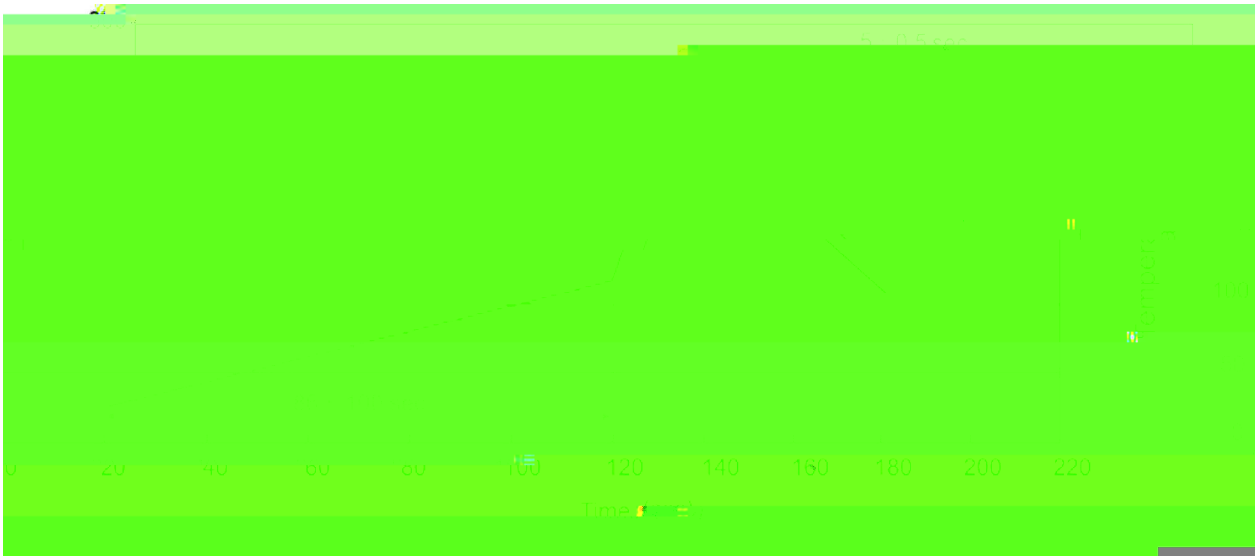
ب ˝ χ

EU=	ﻩ ३ и Ђ
D9 : 6 χ	ﻩ ʒ N Ђ
E=	ﻩ h_{FE} ‘ 6 Ђ
---- χ	ﻩ ı ғ ӈ̋ N Ђ ı ɕ ı ғ ӈ̋ N Ψ ק

Note:

BR:	Company Code.
A673:	Product Type.
B:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ў 25 Ќ 150 ł ı `H ڑ 60 Ќ 90sec;

2 Š Ө □ ў 255 ° 5 ł ı `H ڑ `Y ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ٧ ˛ ɔ ﻩ ў ㎛ 2 Ќ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ў χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

¨Ω ţ ץ Ł / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱